

(19) World Intellectual Property Organization
International Bureau



(43) International Publication Date
7 July 2005 (07.07.2005)

PCT

(10) International Publication Number
WO 2005/062374 A1

(51) International Patent Classification⁷: H01L 21/68, 21/58

(21) International Application Number: PCT/JP2004/018531

(22) International Filing Date: 7 December 2004 (07.12.2004)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data: 2003-426021 24 December 2003 (24.12.2003) JP

(71) Applicant (for all designated States except US): DOW CORNING TORAY CO., LTD. [JP/JP]; 1-3, Marunouchi 1-chome, Chiyoda-ku, Tokyo, 1000005 (JP).

(72) Inventors; and

(75) Inventors/Applicants (for US only): SUTOH, Manabu [JP/JP]; c/o DOW CORNING TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 299-0108 (JP). USHIO, Yoshito [JP/JP]; c/o DOW CORNING TORAY CO., LTD., 2-2, Chigusakaigan, Ichihara-shi, Chiba, 299-0108 (JP).

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

- with international search report
- with amended claims and statement

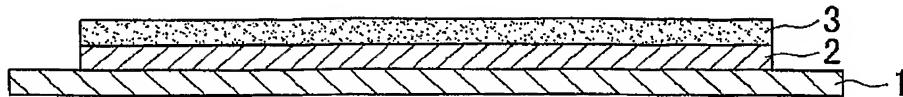
Date of publication of the amended claims and statement:

15 September 2005

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.

WO 2005/062374 A1

(54) Title: DICING/DIE BONDING FILM AND METHOD OF MANUFACTURING THE SAME



(57) Abstract: A dicing/die bonding sheet is made by joining a base film (1) and a silicone based adhesive agent layer (3) through the medium of an undercoat layer (2). This all-in-one dicing/die bonding sheet exhibits superior long-term storage stability and prevents chip delamination during dicing.